

INSTANT BOND Dispensing Machine

- 본 시스템은 Buffer 개념을 도입하여 생산성을 극대화시킨, PCB 혹은 LEAD FRAME상의 정해진 위치에 정량의 액체를 자동으로 토출하는 시스템입니다.
- 고속의 점도포 및 라인도포와 같은 반복작업(Pallet기능) 가능한 제품입니다.
- Jetting, Routing, Mounting, Soldering, Spray의 다양한 디스펜싱에 적용이 가능
- Tray Type 로봇으로서 작업 능률이 향상된 제품.

- It maximizes production by adopting Buffer, and it dispenses fixed volume on PCB or LEAD FRAME.
- It suits for operating fast and repeatedly.(Pallet)
- It's applicable to Jetting, Routing, Mounting, Soldering, Spraying.
- As a Tray Type Robot, work efficiency has been improved.

*APPLICATION



*SPECIFICATION

ROBOT	Stroke (mm)	X axis : 400mm Y axis : 400mm Z axis : 100mm
	Motor	X axis : 100W AC Servo MOTOR Y axis : 200W AC Servo MOTOR Z axis : 100W AC Servo MOTOR, adhesion BRAKE
	Speed	X axis, Y axis : 500mm/sec Z axis : 250mm/sec
	LAY OUT	890(W) x 750(D) x 1615(H) – Including Table (Unit : mm)
	Repeatability (mm) Payload (kgf)	X, Y : ± 0.02 Z : ± 0.01 X1, Y axis : 20 kgf Z axis : 7 kgf
Dispensing part	1~5 axis Barrel Type(Teflon Hose Type)	
Fluid line	i) Use 5~50CC BARREL ii) Tubing Controller(SD400 series) : able to use many axis	
PICK UP UNIT	Vacuum Pick-Up Unit	
Needle(Hose)	Teflon Needle, Teflon Hose	
JIG	Able to adhesive and come off, the equipment occurring vacuum	